

Optical trends in Interconnects

Ronald P. Luijten

Manager high speed switching group

IBM Zurich Research Laboratory, Rüschlikon, Switzerland

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My car story



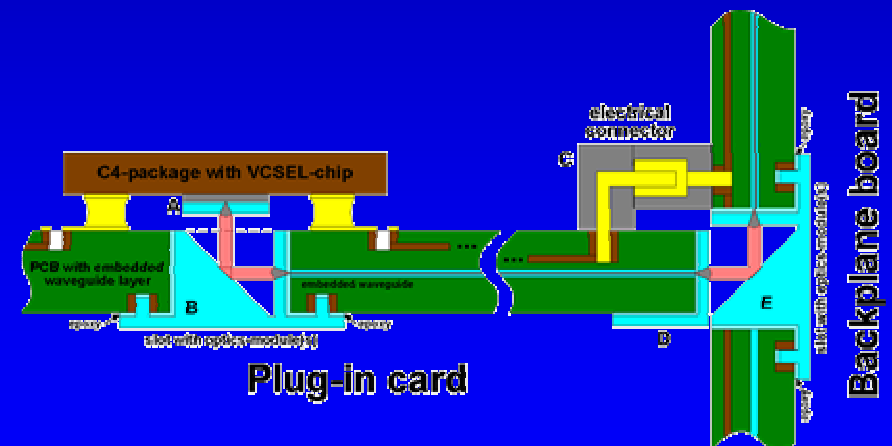
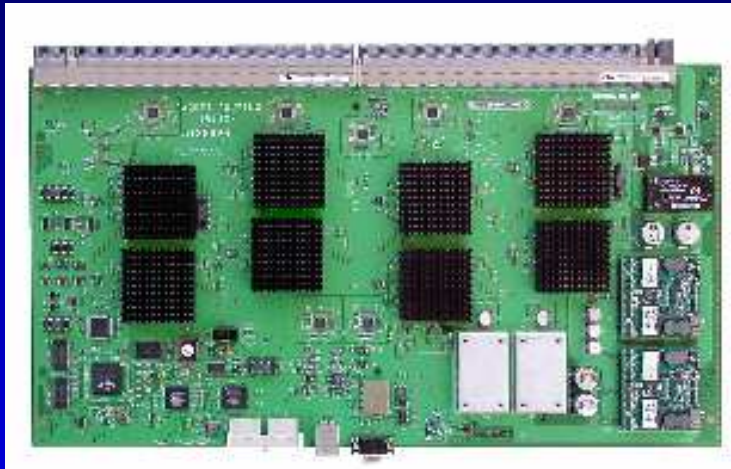
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Our Zurich lab research activities



... relevant to this audience



Lessons learned



$$\text{FoM} = \text{Gbps} / \text{Watt} * \text{Inch}^3$$

PRIZMA-5

30 W/15W

PRIZMA-4

24 W/10W

PRIZMA-3

15 W/5W

PRIZMA-2

10 W/1.5W

PRIZMA

10 W/ 1.5W

Lessons learned (2)



**But
\$ / Gbps also counts...**

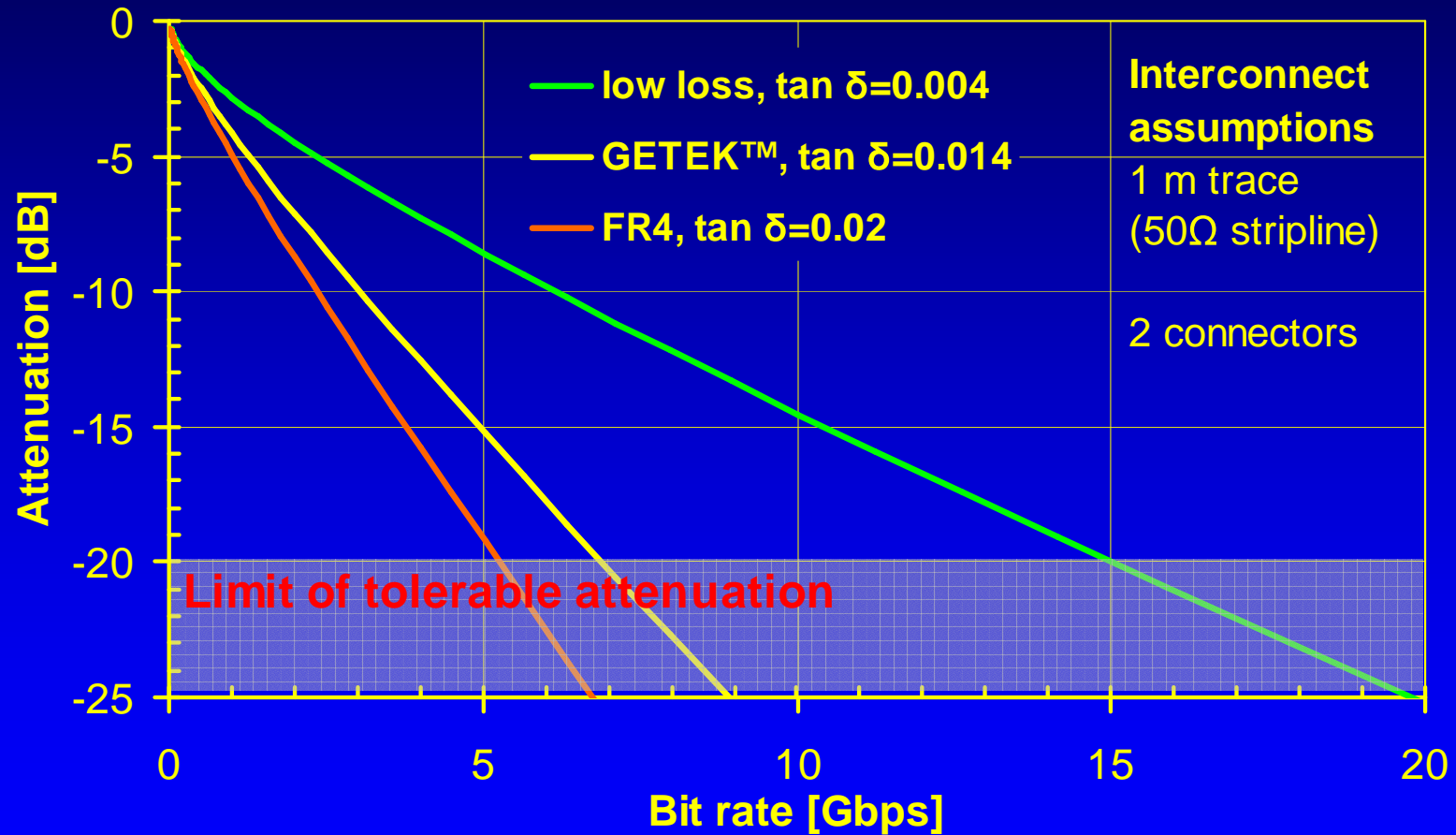
Stick with CMOS

Do not run at highest clock speed...

Board attenuation



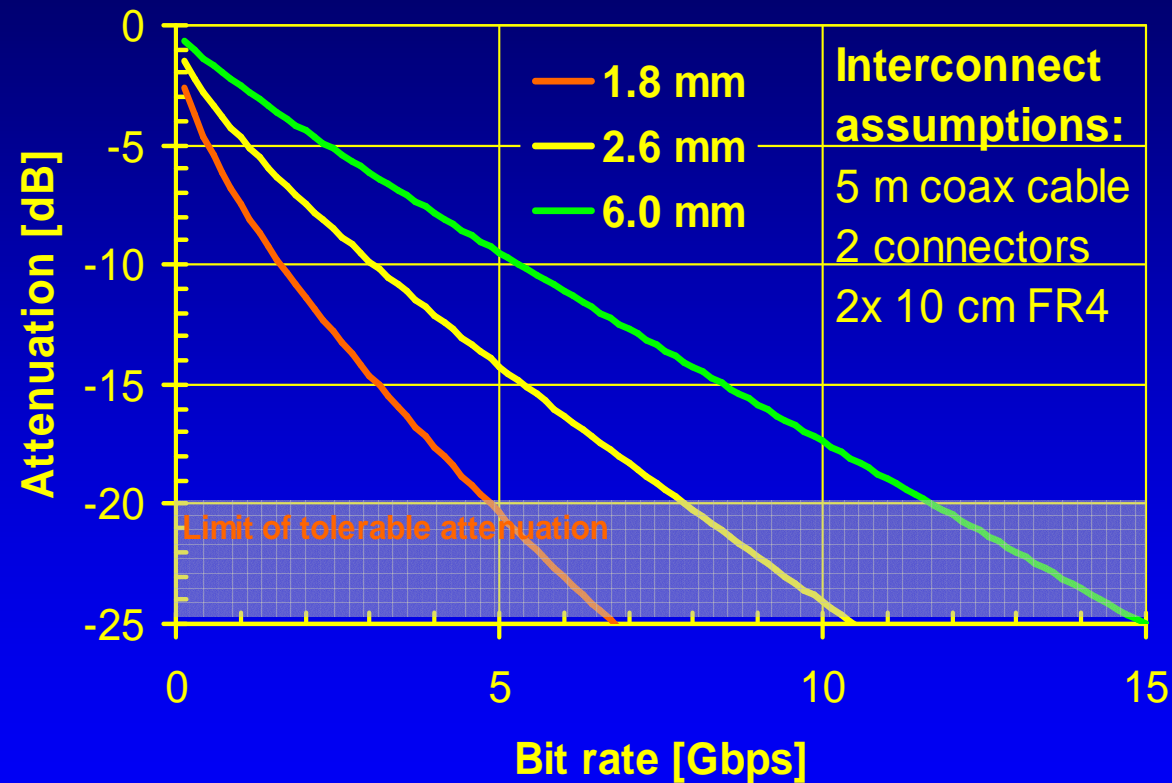
Attenuation vs. bit rate for various board materials



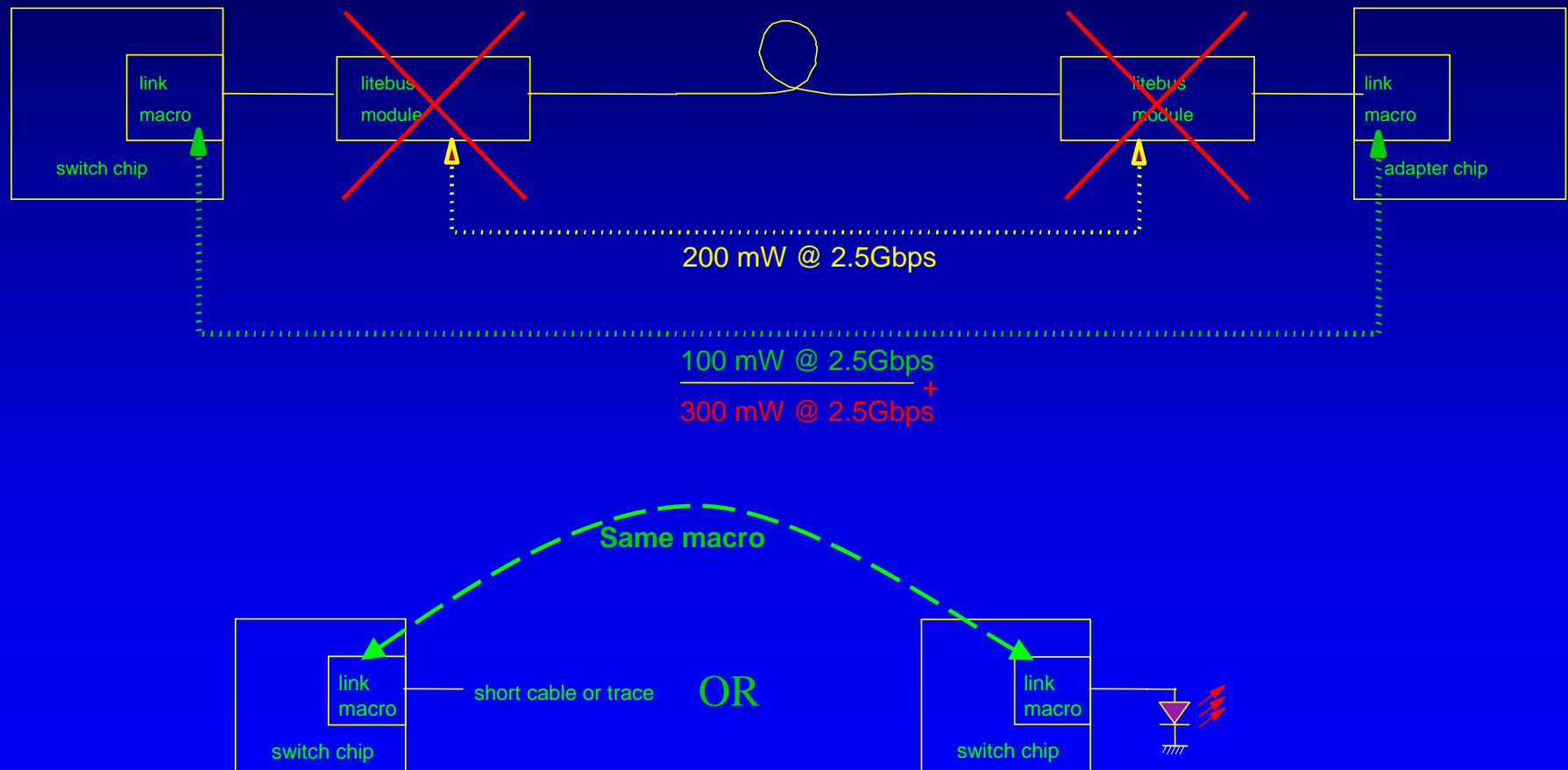
Cable attenuation



Attenuation vs. bit rate for various cable diameters



Optimizing power consumption





- **Key Features**

- Simple waveguide structures
- Potentially cheap and mass-producible
- Integrated passive alignment features
- Various compatible connectors (device-to-board, board-to-backplane, backplane-to-fiber)

observations



**Optics – do NOT give bandwidth
But give distance!**

All optical components are there:

VCSEL

Detector

Fiber

FR4 waveguide

Except cost effective packaging...!

And all optical switching ??



Active optical switch element	1/2
Optical memory	no
Optical header processing	no

Concluding remarks



Optics coming intra-rack: power

Work needed in packaging

**All optical switching:
more time needed**

**Next gen interconnect
Electronic processing
Optical transport**